MPC

MULTI PROJEKT CHIP GRUPPE <u>BADEN-WÜRTTEMBERG</u>

66. WORKSHOP **ON MICROELECTRONICS**

June 30th, 2023 // Ulm University of Applied Sciences, Germany

CALL FOR PAPERS



Topics

- Analog, Mixed-Signal, and Digital Circuit Design
- Application-Specific Integrated Circuits (ASICs)
- Electronic Systems Design
- Embedded Systems
- FPGA/CPLD Design
- PCB Design
- Electronic Design Automation



Microelectronics Education

Important Dates

Submission of contributions June 2nd, 2023 Notification of acceptance June 9th, 2023

A prize will be awarded for the best student presentation

Steering Committee D. Benyoucef, H.-P. Bürkle, J. Gerlach, R. Gessler, J. Giehl, E. Hennig, F. Kesel, E. Mackensen, H.-J. Ng, W. Lindermeir, C. Schick, A. Siggelkow, A. Terzis Program Committee E. Hennig, L. Schmidt, A. Terzis Local Organisation L. Schmidt, A. Terzis (Ulm University of Applied Sciences) Conference Language German and English







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